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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc504-i-mv

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICKit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

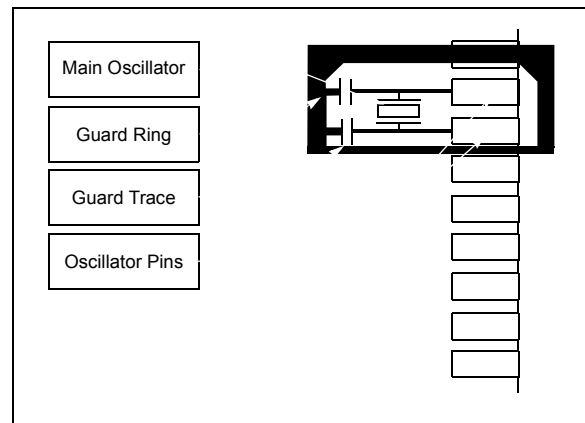
- "Using MPLAB® ICD 3" (poster) DS51765
- "MPLAB® ICD 3 Design Advisory" DS51764
- "MPLAB® REAL ICE™ In-Circuit Emulator User's Guide" DS51616
- "Using MPLAB® REAL ICE™ In-Circuit Emulator" (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to $3 \text{ MHz} < F_{IN} < 5.5 \text{ MHz}$ to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between Vss and unused pins, and drive the output to logic low.

2.9 Application Examples

- Induction heating
- Uninterruptable Power Supplies (UPS)
- DC/AC inverters
- Compressor motor control
- Washing machine 3-phase motor control
- BLDC motor control
- Automotive HVAC, cooling fans, fuel pumps
- Stepper motor control
- Audio and fluid sensor monitoring
- Camera lens focus and stability control
- Speech (playback, hands-free kits, answering machines, VoIP)
- Consumer audio
- Industrial and building control (security systems and access control)
- Barcode reading
- Networking: LAN switches, gateways
- Data storage device management
- Smart cards and smart card readers

Examples of typical application connections are shown in Figure 2-4 through Figure 2-8.

FIGURE 2-4: BOOST CONVERTER IMPLEMENTATION

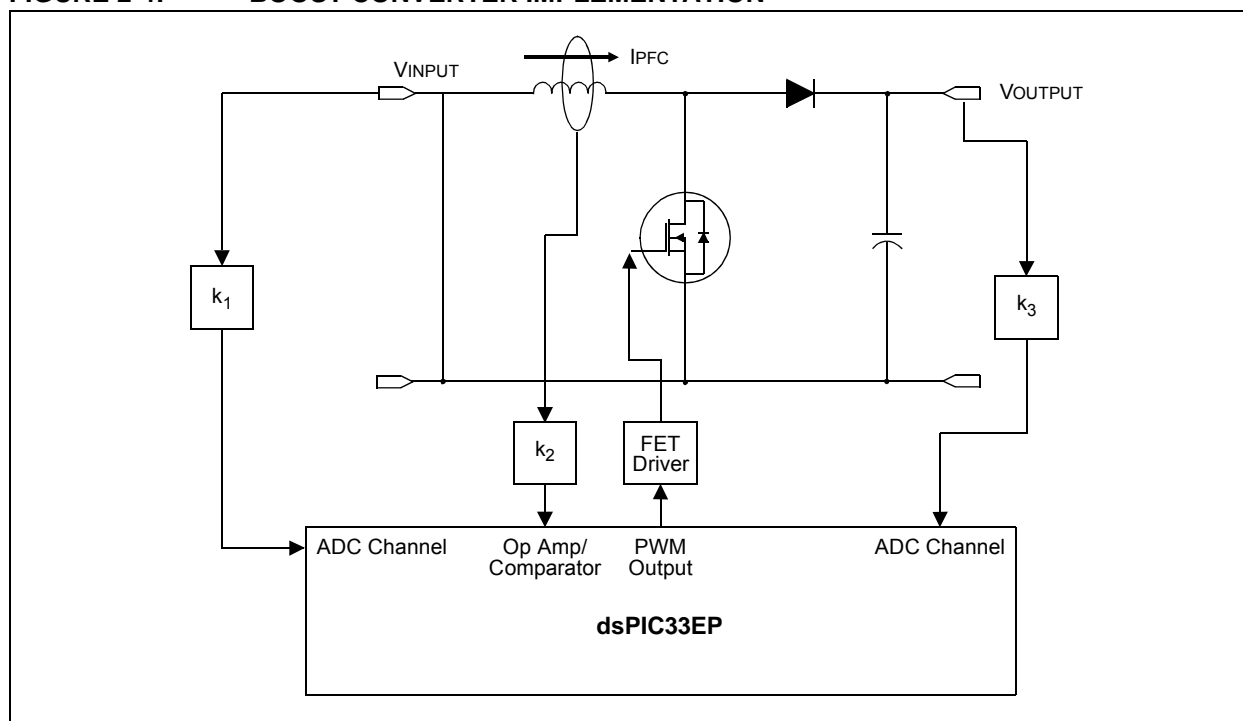
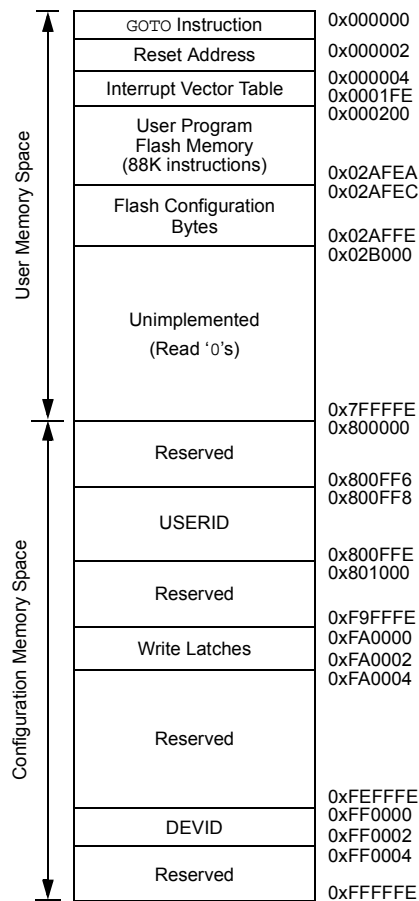


FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X AND PIC24EP256GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-21: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 0 OR 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

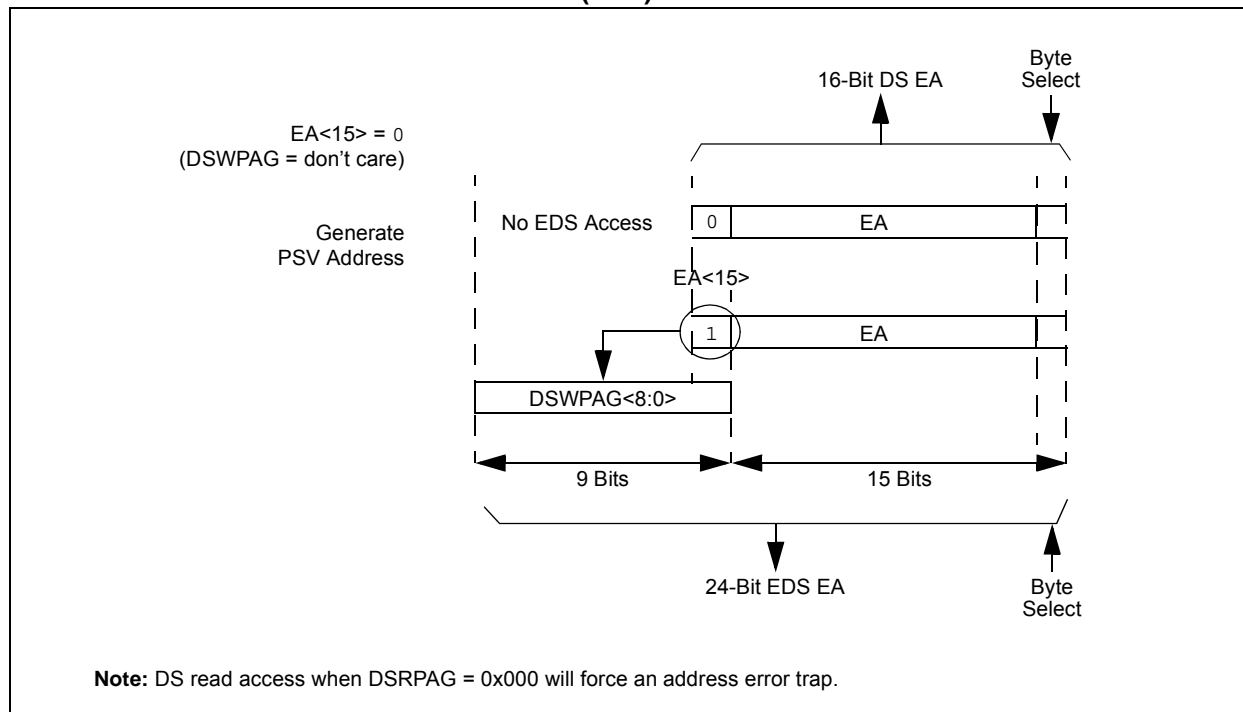
File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1CTRL1	0400	—	—	CSIDL	ABAT	CANCKS	REQOP<2:0>			OPMODE<2:0>			—	CANCAP	—	—	WIN	0480
C1CTRL2	0402	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C1VEC	0404	—	—	—	FILHIT<4:0>					—	ICODE<6:0>							0040
C1FCTRL	0406	DMABS<2:0>			—	—	—	—	—	—	—	—	FSA<4:0>					0000
C1FIFO	0408	—	—	FBP<5:0>						—	—	FNRB<5:0>						0000
C1INTF	040A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C1INTE	040C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C1EC	040E	TERRCNT<7:0>								RERRCNT<7:0>								0000
C1CFG1	0410	—	—	—	—	—	—	—	—	SJW<1:0>		BRP<5:0>						0000
C1CFG2	0412	—	WAKFIL	—	—	—	SEG2PH<2:0>			SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>			0000
C1FEN1	0414	FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8	FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0	FFFF
C1FMSKSEL1	0418	F7MSK<1:0>		F6MSK<1:0>		F5MSK<1:0>		F4MSK<1:0>		F3MSK<1:0>		F2MSK<1:0>		F1MSK<1:0>		F0MSK<1:0>		0000
C1FMSKSEL2	041A	F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>		F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>		0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-22: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 0 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1RXFUL1	0420	RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8	RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0	0000
C1RXFUL2	0422	RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24	RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16	0000
C1RXOVF1	0428	RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8	RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0	0000
C1RXOVF2	042A	RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24	RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16	0000
C1TR01CON	0430	TXEN1	TXABT1	TXLARB1	TXERR1	TXREQ1	RTREN1	TX1PRI<1:0>		TXEN0	TXABAT0	TXLARB0	TXERR0	TXREQ0	RTREN0	TX0PRI<1:0>		0000
C1TR23CON	0432	TXEN3	TXABT3	TXLARB3	TXERR3	TXREQ3	RTREN3	TX3PRI<1:0>		TXEN2	TXABAT2	TXLARB2	TXERR2	TXREQ2	RTREN2	TX2PRI<1:0>		0000
C1TR45CON	0434	TXEN5	TXABT5	TXLARB5	TXERR5	TXREQ5	RTREN5	TX5PRI<1:0>		TXEN4	TXABAT4	TXLARB4	TXERR4	TXREQ4	RTREN4	TX4PRI<1:0>		0000
C1TR67CON	0436	TXEN7	TXABT7	TXLARB7	TXERR7	TXREQ7	RTREN7	TX7PRI<1:0>		TXEN6	TXABAT6	TXLARB6	TXERR6	TXREQ6	RTREN6	TX6PRI<1:0>		xxxx
C1RXD	0440	ECAN1 Receive Data Word																xxxx
C1TXD	0442	ECAN1 Transmit Data Word																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

EXAMPLE 4-2: EXTENDED DATA SPACE (EDS) WRITE ADDRESS GENERATION

The paged memory scheme provides access to multiple 32-Kbyte windows in the EDS and PSV memory. The Data Space Page registers, DSxPAG, in combination with the upper half of the Data Space address, can provide up to 16 Mbytes of additional address space in the EDS and 8 Mbytes (DSRPAG only) of PSV address space. The paged data memory space is shown in Example 4-3.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG. Writes to PS are not supported, so DSWPAG is dedicated to DS, including EDS only. The Data Space and EDS can be read from, and written to, using DSRPAG and DSWPAG, respectively.

4.6 Modulo Addressing (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X Devices Only)

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either Data or Program Space (since the Data Pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into Program Space) and Y Data Spaces. Modulo Addressing can operate on any W Register Pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can be configured to operate in only one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.6.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified, and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note: Y space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.6.2 W ADDRESS REGISTER SELECTION

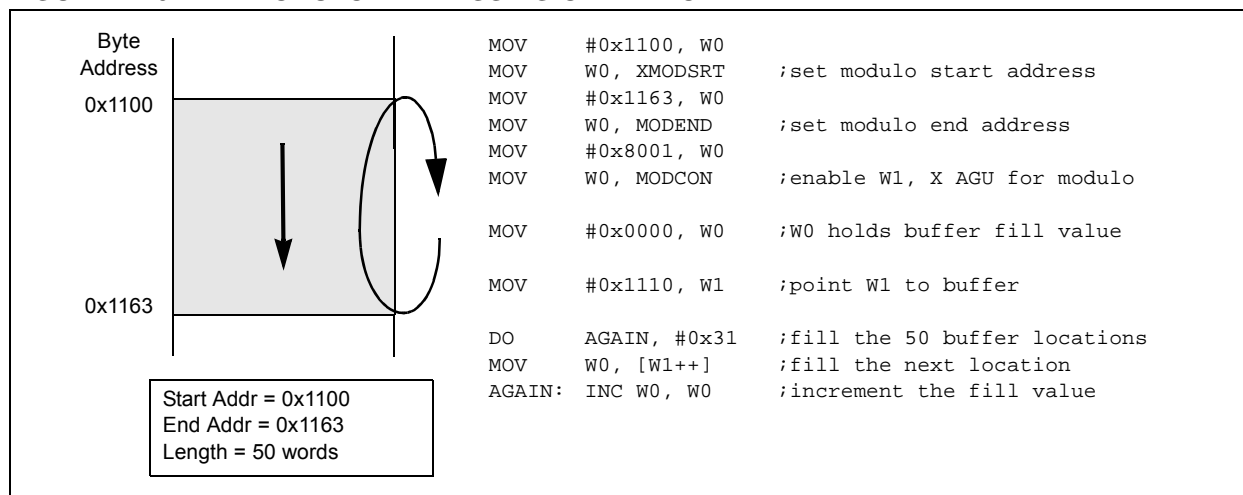
The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that operate with Modulo Addressing:

- If XWM = 1111, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = 1111, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W register (XWM), to which Modulo Addressing is to be applied, is stored in MODCON<3:0> (see Table 4-1). Modulo Addressing is enabled for X Data Space when XWM is set to any value other than '1111' and the XMODEN bit is set (MODCON<15>).

The Y Address Space Pointer W register (YWM), to which Modulo Addressing is to be applied, is stored in MODCON<7:4>. Modulo Addressing is enabled for Y Data Space when YWM is set to any value other than '1111' and the YMODEN bit is set at MODCON<14>.

FIGURE 4-20: MODULO ADDRESSING OPERATION EXAMPLE



16.3 PWMx Control Registers

REGISTER 16-1: PTCN: PWMx TIME BASE CONTROL REGISTER

R/W-0	U-0	R/W-0	HS/HC-0	R/W-0	R/W-0	R/W-0	R/W-0
PTEN	—	PTSIDL	SESTAT	SEIEN	EIPU ⁽¹⁾	SYNCPOL ⁽¹⁾	SYNCOEN ⁽¹⁾
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SYNCEN ⁽¹⁾	SYNCSRC2 ⁽¹⁾	SYNCSRC1 ⁽¹⁾	SYNCSRC0 ⁽¹⁾	SEVTPS3 ⁽¹⁾	SEVTPS2 ⁽¹⁾	SEVTPS1 ⁽¹⁾	SEVTPS0 ⁽¹⁾
bit 7				bit 0			

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

- bit 15 **PTEN:** PWMx Module Enable bit
1 = PWMx module is enabled
0 = PWMx module is disabled
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **PTSIDL:** PWMx Time Base Stop in Idle Mode bit
1 = PWMx time base halts in CPU Idle mode
0 = PWMx time base runs in CPU Idle mode
- bit 12 **SESTAT:** Special Event Interrupt Status bit
1 = Special event interrupt is pending
0 = Special event interrupt is not pending
- bit 11 **SEIEN:** Special Event Interrupt Enable bit
1 = Special event interrupt is enabled
0 = Special event interrupt is disabled
- bit 10 **EIPU:** Enable Immediate Period Updates bit⁽¹⁾
1 = Active Period register is updated immediately
0 = Active Period register updates occur on PWMx cycle boundaries
- bit 9 **SYNCPOL:** Synchronize Input and Output Polarity bit⁽¹⁾
1 = SYNCI1/SYNCO1 polarity is inverted (active-low)
0 = SYNCI1/SYNCO1 is active-high
- bit 8 **SYNCOEN:** Primary Time Base Sync Enable bit⁽¹⁾
1 = SYNCO1 output is enabled
0 = SYNCO1 output is disabled
- bit 7 **SYNCEN:** External Time Base Synchronization Enable bit⁽¹⁾
1 = External synchronization of primary time base is enabled
0 = External synchronization of primary time base is disabled

Note 1: These bits should be changed only when PTEN = 0. In addition, when using the SYNCI1 feature, the user application must program the period register with a value that is slightly larger than the expected period of the external synchronization input signal.

2: See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for information on this selection.

REGISTER 19-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15						bit 8	

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7						bit 0	

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-10

Unimplemented: Read as '0'

bit 9-0

AMSK<9:0>: Address Mask Select bits

For 10-Bit Address:

1 = Enables masking for bit Ax of incoming message address; bit match is not required in this position

0 = Disables masking for bit Ax; bit match is required in this position

For 7-Bit Address (I2CxMSK<6:0> only):

1 = Enables masking for bit Ax + 1 of incoming message address; bit match is not required in this position

0 = Disables masking for bit Ax + 1; bit match is required in this position

REGISTER 21-24: CxRXOVF1: ECANx RECEIVE BUFFER OVERFLOW REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0
bit 7							bit 0

Legend: C = Writable bit, but only '0' can be written to clear the bit
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **RXOVF<15:0>:** Receive Buffer n Overflow bits
1 = Module attempted to write to a full buffer (set by module)
0 = No overflow condition (cleared by user software)

REGISTER 21-25: CxRXOVF2: ECANx RECEIVE BUFFER OVERFLOW REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16
bit 7							bit 0

Legend: C = Writable bit, but only '0' can be written to clear the bit
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **RXOVF<31:16>:** Receive Buffer n Overflow bits
1 = Module attempted to write to a full buffer (set by module)
0 = No overflow condition (cleared by user software)

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'
 bit 12-2 **SID<10:0>:** Standard Identifier bits
 bit 1 **SRR:** Substitute Remote Request bit
 When IDE = 0:
 1 = Message will request remote transmission
 0 = Normal message
 When IDE = 1:
 The SRR bit must be set to '1'.
 bit 0 **IDE:** Extended Identifier bit
 1 = Message will transmit Extended Identifier
 0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'
 bit 11-0 **EID<17:6>:** Extended Identifier bits

26.0 PROGRAMMABLE CYCLIC REDUNDANCY CHECK (CRC) GENERATOR

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Programmable Cyclic Redundancy Check (CRC)**” (DS70346) of the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The programmable CRC generator offers the following features:

- User-programmable (up to 32nd order) polynomial CRC equation
- Interrupt output
- Data FIFO

The programmable CRC generator provides a hardware implemented method of quickly generating checksums for various networking and security applications. It offers the following features:

- User-programmable CRC polynomial equation, up to 32 bits
- Programmable shift direction (little or big-endian)
- Independent data and polynomial lengths
- Configurable interrupt output
- Data FIFO

A simplified block diagram of the CRC generator is shown in Figure 26-1. A simple version of the CRC shift engine is shown in Figure 26-2.

FIGURE 26-1: CRC BLOCK DIAGRAM

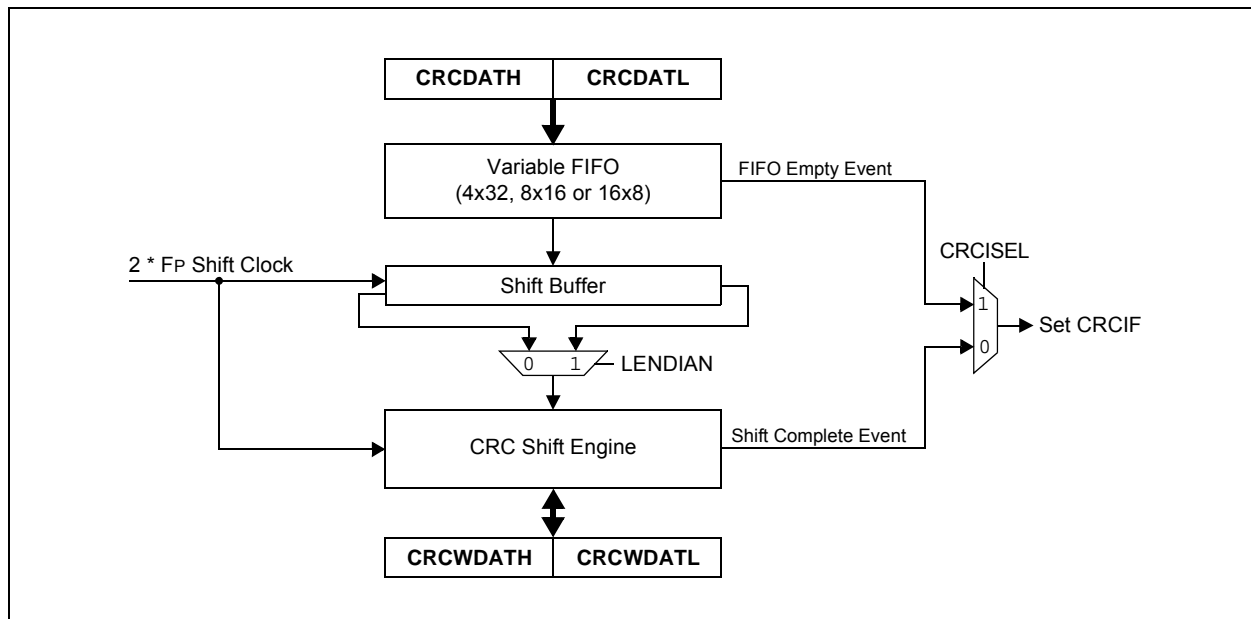


TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DI10	V _{IL}	Input Low Voltage Any I/O Pin and $\overline{\text{MCLR}}$	V _{SS}	—	0.2 V _{DD}	V	
DI18		I/O Pins with SDAx, SCLx	V _{SS}	—	0.3 V _{DD}	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	V _{SS}	—	0.8	V	SMBus enabled
DI20	V _{IH}	Input High Voltage I/O Pins Not 5V Tolerant	0.8 V _{DD}	—	V _{DD}	V	(Note 3)
		I/O Pins 5V Tolerant and $\overline{\text{MCLR}}$	0.8 V _{DD}	—	5.5	V	(Note 3)
		I/O Pins with SDAx, SCLx	0.8 V _{DD}	—	5.5	V	SMBus disabled
		I/O Pins with SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
DI30	ICNPU	Change Notification Pull-up Current	150	250	550	μA	V _{DD} = 3.3V, V _{PIN} = V _{SS}
DI31	ICNPD	Change Notification Pull-Down Current⁽⁴⁾	20	50	100	μA	V _{DD} = 3.3V, V _{PIN} = V _{DD}

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the “Pin Diagrams” section for the 5V tolerant I/O pins.

4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

5: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

**TABLE 30-45: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 15	MHz	(Note 3)
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1} \downarrow$ to SCK1 \uparrow or SCK1 \downarrow Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1} \uparrow$ to SDO1 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH, TscL2ssH	$\overline{SS1} \uparrow$ after SCK1 Edge	1.5 Tcy + 40	—	—	ns	(Note 4)
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

**TABLE 30-46: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of Fp or 11	MHz	(Note 3)
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1} \downarrow$ to SCK1 \uparrow or SCK1 \downarrow Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1} \uparrow$ to SDO1 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH, TscL2ssH	$\overline{SS1} \uparrow$ after SCK1 Edge	1.5 Tcy + 40	—	—	ns	(Note 4)
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-56: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
CTMU Current Source							
CTMUI1	IOUT1	Base Range ⁽¹⁾	0.29	—	0.77	μA	CTMUICON<9:8> = 01
CTMUI2	IOUT2	10x Range ⁽¹⁾	3.85	—	7.7	μA	CTMUICON<9:8> = 10
CTMUI3	IOUT3	100x Range ⁽¹⁾	38.5	—	77	μA	CTMUICON<9:8> = 11
CTMUI4	IOUT4	1000x Range ⁽¹⁾	385	—	770	μA	CTMUICON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage ^(1,2)	—	0.598	—	V	T _A = +25°C, CTMUICON<9:8> = 01
			—	0.658	—	V	T _A = +25°C, CTMUICON<9:8> = 10
			—	0.721	—	V	T _A = +25°C, CTMUICON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change ^(1,2,3)	—	-1.92	—	mV/°C	CTMUICON<9:8> = 01
			—	-1.74	—	mV/°C	CTMUICON<9:8> = 10
			—	-1.56	—	mV/°C	CTMUICON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUICON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing.

3: Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC configured for 10-bit mode
- ADC module configured for conversion speed of 500 ksp/s
- All PMDx bits are cleared (PMDx = 0)
- Executing a while(1) statement
- Device operating from the FRC with no PLL

FIGURE 30-37: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS
(CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRG = 0)

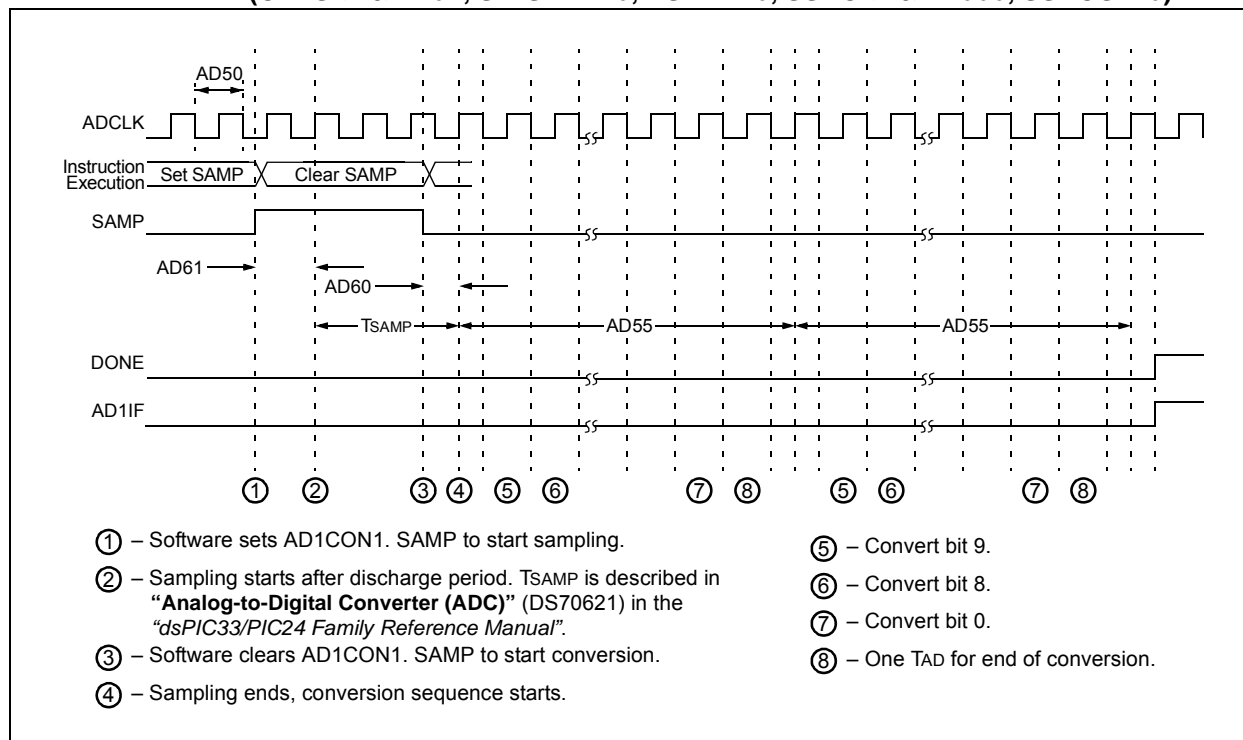


FIGURE 30-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRG = 0, SAMC<4:0> = 00010)

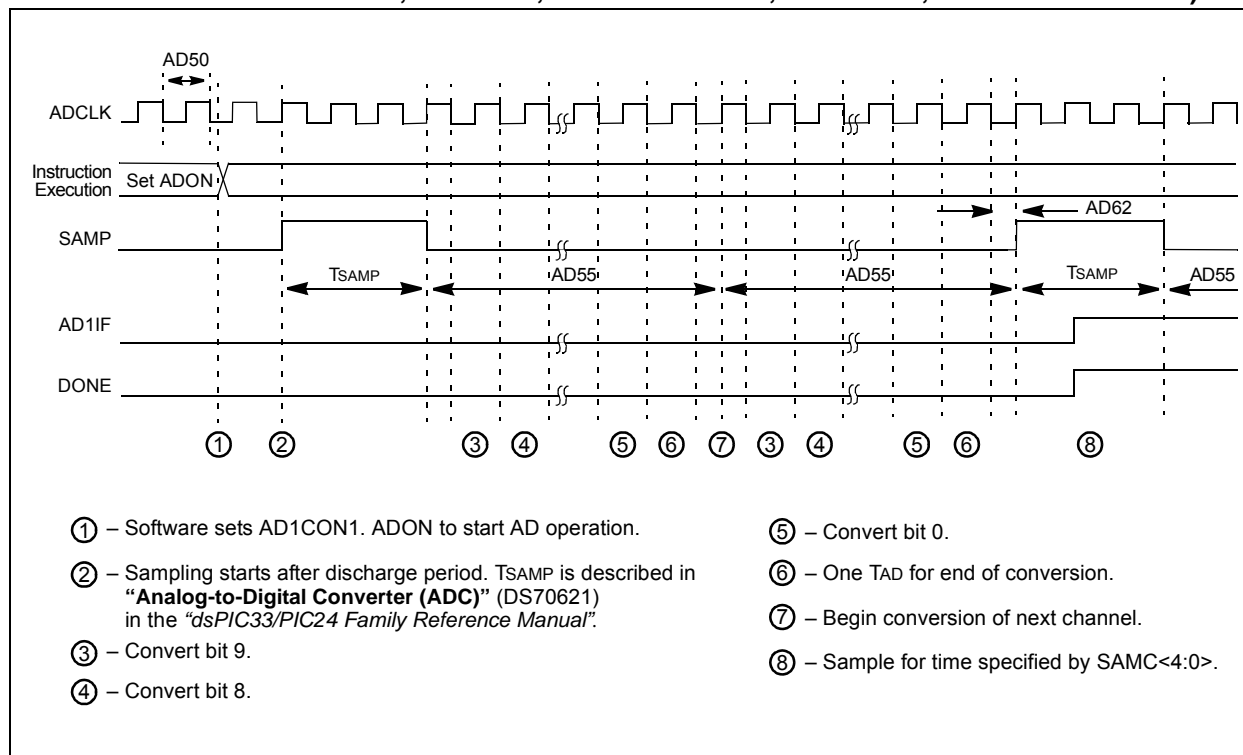


FIGURE 32-9: TYPICAL FRC FREQUENCY @ VDD = 3.3V

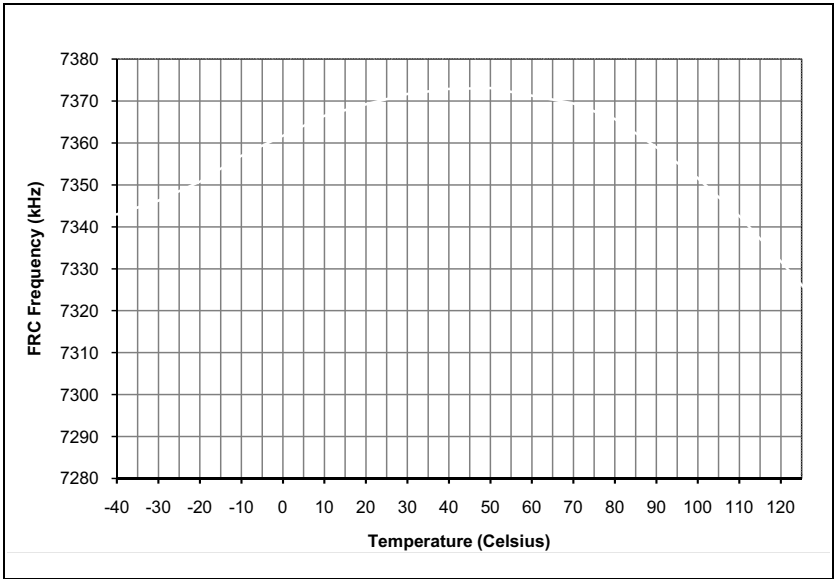


FIGURE 32-10: TYPICAL LPRC FREQUENCY @ VDD = 3.3V

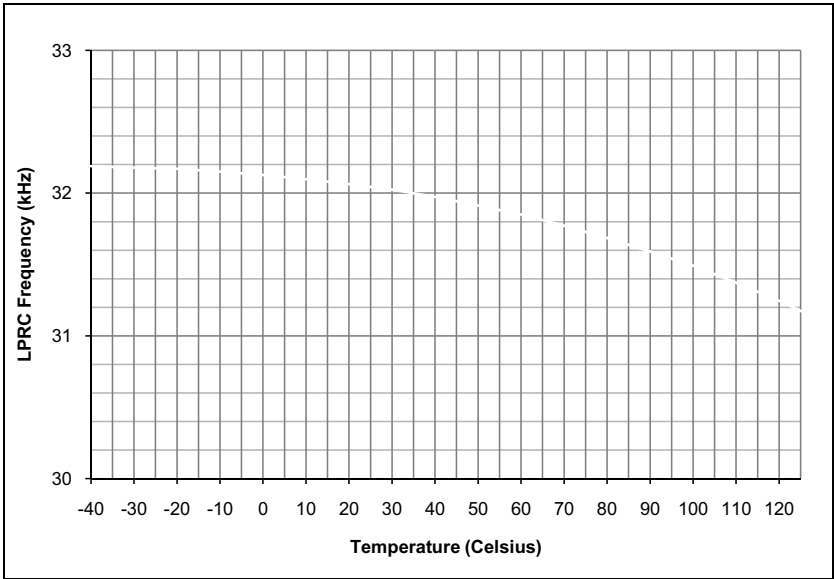
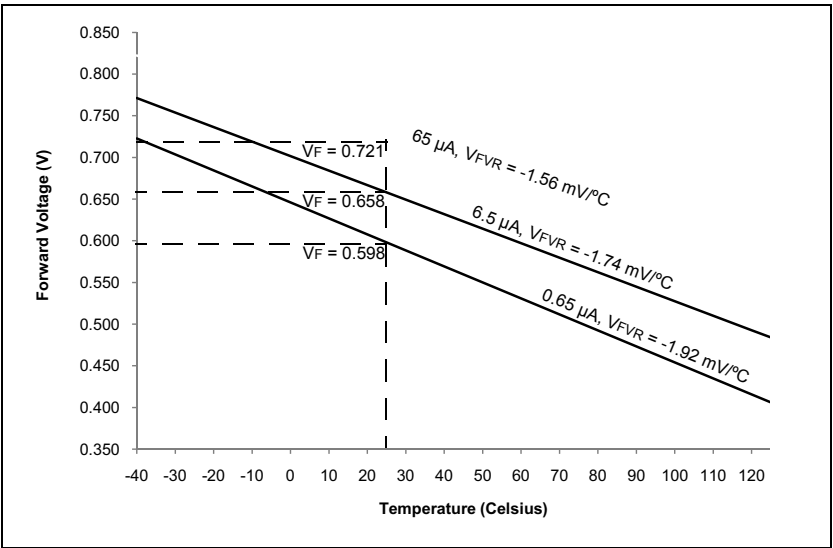
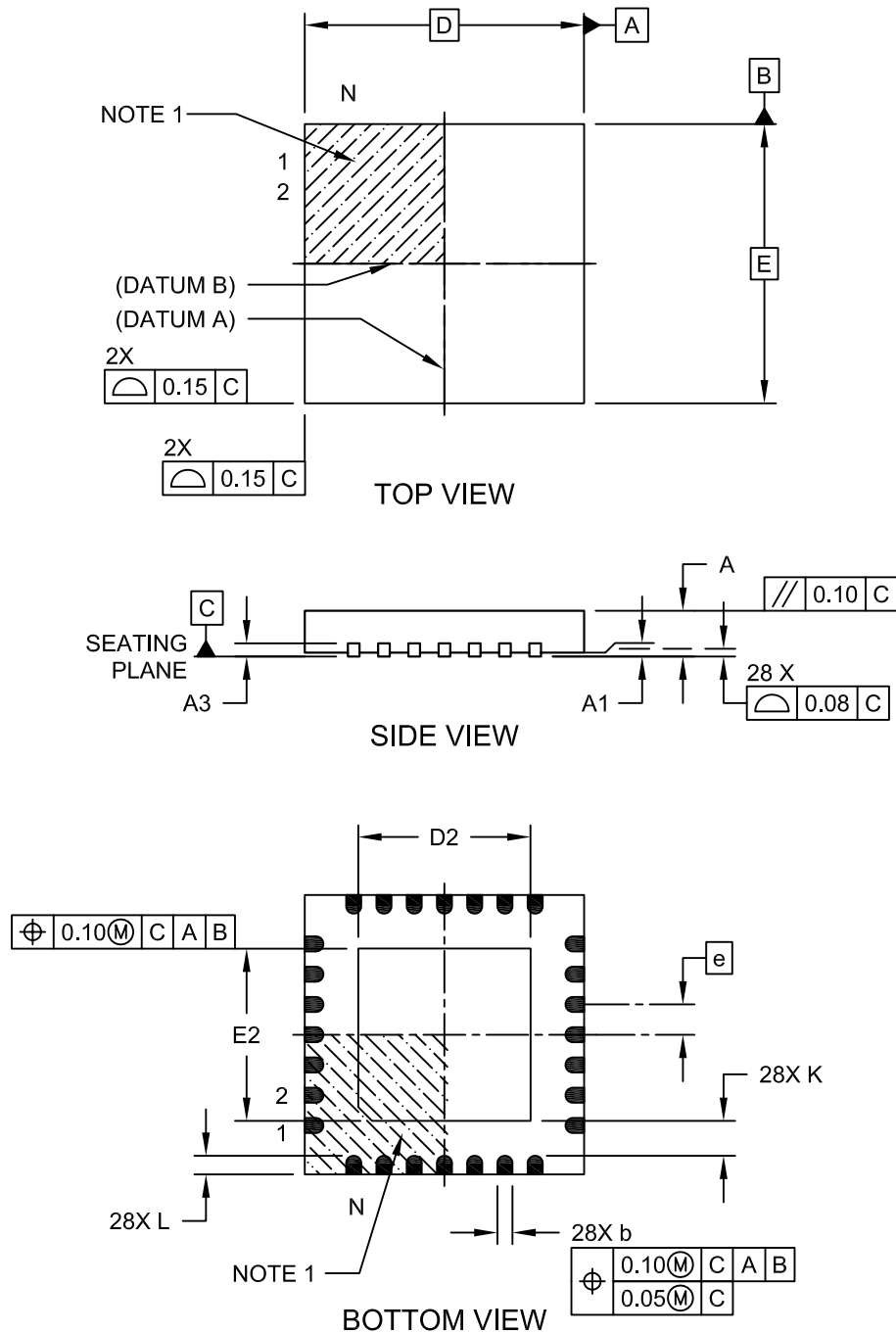


FIGURE 32-11: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



**28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S]
With 0.40 mm Terminal Length**

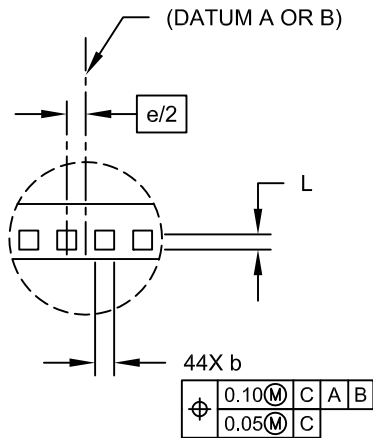
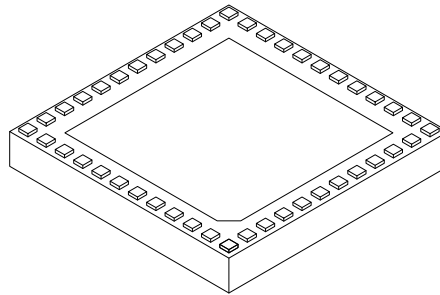
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

**DETAIL A**

Dimension	Units	MILLIMETERS		
	Limits	MIN	NOM	MAX
Number of Pins	N	44		
Number of Pins per Side	ND	12		
Number of Pins per Side	NE	10		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

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